

N-channel 60 V, 6.6 mΩtyp., 77 A STripFET[™] VI DeepGATE[™] Power MOSFET in a TO-220 package

Datasheet - production data

Features

| Order code | V_{DS} | R _{DS(on)} max | I _D | P _{TOT} |
|------------|-----------------|--------------------------------|----------------|------------------|
| STP77N6F6 | 60 V | 7.9 mΩ (V _{GS} =10 V) | 77 A | 80 W |

- R_{DS(on)} * Q_g industry benchmark
- Extremely low on-resistance R_{DS(on)}
- High avalanche ruggedness
- Low gate drive power losses
- Very low switching gate charge

Applications

Switching applications

Description

This device is an N-channel Power MOSFET developed using the 6th generation of STripFETTM DeepGATETM technology, with a new gate structure. The resulting Power MOSFET exhibits the lowest $R_{DS(on)}$ in all packages.

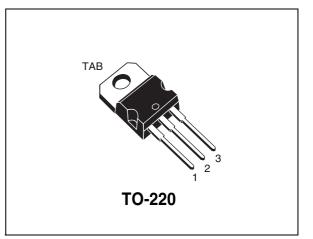


Figure 1. Internal schematic diagram

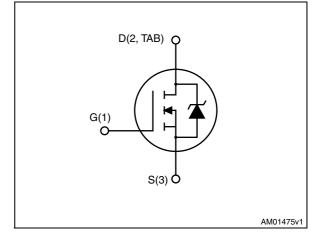


Table 1. Device summary

| Order code | Marking | Package | Packaging |
|------------|---------|---------|-----------|
| STP77N6F6 | 77N6F6 | TO-220 | Tube |

This is information on a product in full production.

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1 Electrical ratings

| Table 2. | Absolute | maximum | ratings |
|----------|----------|---------------|---------|
| | Absolute | IIIaAIIIIaIII | raungs |

| Symbol | Parameter | Value | Unit |
|--------------------------------|---|------------|------|
| V_{DS} | Drain-source voltage | 60 | v |
| V _{GS} | Gate-source voltage | ±20 | v |
| ۱ _D (1) | Drain current (continuous) at T _c = 25 °C | 77 | |
| ۱ _D ⁽¹⁾ | Drain current (continuous) at T _c = 100 °C | 55 | Α |
| I _{DM} ⁽²⁾ | Drain Current (pulsed) | 308 | |
| P _{TOT} (1) | Total dissipation at $T_c = 25 \text{ °C}$ | 80 | W |
| T _{J Pstg} | Operating junction temperature storage temperature | -55 to 175 | °C |

1. This value is rated according to Rthj-c

2. Pulse width is limited by safe operating area

| Table 3. | Thermal data |
|----------|--------------|
|----------|--------------|

| Symbol | Parameter | Value | Unit |
|-----------------------------------|-------------------------------------|-------|------|
| R _{thj-c} | Thermal resistance junction-case | 1.88 | °C/W |
| R _{thj-a} ⁽¹⁾ | Thermal resistance junction-ambient | 62.5 | 0/1 |

1. When mounted on FR-4 board of 1 inch², 2 oz Cu, t < 10 sec

| Table 4. | Avalache | characteristics |
|----------|----------|-----------------|
| | | |

| Symbol | Parameter | Value | Unit |
|-----------------|---|-------|------|
| I _{AR} | Avalanche current, repetitive or not-repetitive (pulse width limited by maximum junction temperature) | TBD | A |
| E _{AS} | Single pulse avalanche energy ($T_J = 25 \text{ °C}, I_D = I_{AR}, V_{DD} = 14 \text{ V}$) | TBD | mJ |



2 Electrical characteristics

(T_J= 25 °C unless otherwise specified)

| Symbol | Parameter | Test conditions | Min. | Тур. | Max. | Unit |
|----------------------|---|--|------|------|-------|------|
| V _{(BR)DSS} | Drain-source breakdown voltage (V _{GS} = 0) | I _D = 250 μA | 60 | | | v |
| Zero gate voltage | V _{DS} = 60 V | | | 10 | μΑ | |
| IDSS | Drain current (V _{GS} = 0) | V _{DS} = 60 V, T _J =125 °C | | | 100 | μA |
| I _{GSS} | Gate-body leakage current (V _{DS} = 0) | V _{GS} = ± 20 V | | | ± 100 | v |
| V _{GS(th)} | Gate threshold voltage | $V_{DS} = V_{GS}, I_D = 250 \ \mu A$ | 2 | | 4 | V |
| R _{DS(on)} | Static drain-source on- resistance | V _{GS} = 10 V, I _D = 33 A | | 6.6 | 7.9 | Ω |

Table 5. On/off states

Table 6. Dynamic

| Symbol | Parameter | Test conditions | Min. | Тур. | Max. | Unit |
|------------------|---------------------------------|--|------|------|------|------|
| C _{iss} | Input capacitance | | | 5300 | | |
| C _{oss} | Output capacitance | V _{DS} = 25 V, f = 1 MHz, V _{GS} = 0 | - | 1290 | - | pF |
| C _{rss} | Reverse transfer capacitance | $V_{GS} = 0$ | | 217 | | Ρ. |
| Qg | Total gate charge | | | 76 | | |
| Q _{gs} | Gate-source charge | V _{DD} = 30 V, I _D = 77 A, V _{GS} = 10 V | - | TBD | - | nC |
| Q _{gd} | Gate-drain charge | | | TBD | | |
| R _g | Intrinsic gate resistance | f = 1 MHz open drain | - | 3.6 | - | Ω |

Table 7. Switching times

| Symbol | Parameter | Test conditions | Min. | Тур. | Max. | Unit |
|---------------------------------------|----------------------------------|--|------|------|------|------|
| t _{d(on)} t _r | Turn-on delay time Rise time | V _{DD} = 30 V, I _D = 33A | - | TBD | - | 20 |
| t _{d(off)} t _f | Turn-off-delay time Fall time | $R_{G} = 4.7 \Omega V_{GS} = 10 V$ | - | ששו | - | ns |



| Symbol | Parameter | Test conditions | Min. | Тур. | Max. | Unit |
|---------------------------------|-------------------------------|--|------|------|------|------|
| I _{SD} | Source-drain current | | - | | 77 | А |
| I _{SDM} ⁽¹⁾ | Source-drain current (pulsed) | | - | | 308 | A |
| V _{SD} ⁽²⁾ | Forward on voltage | $I_{SD} = 77 \text{ A}, V_{GS} = 0$ | - | | | V |
| t _{rr} | Reverse recovery time | $I_{SD} = 77 \text{ A}, V_{DD} = 80 \text{ V}$ | | | | ns |
| Q _{rr} | Reverse recovery charge | di/dt = 100 A/µs, | - | TBD | TBD | nC |
| I _{RRM} | Reverse recovery current | T _j = 150 °C | | | | А |

Table 8.Source drain diode

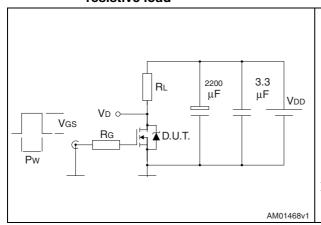
1. Pulse width is limited by safe operating area

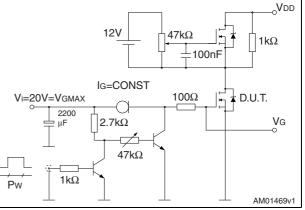
2. Pulse test: pulse duration = 300 μ s, duty cycle 1.5%



3 Test circuits

Figure 2. Switching times test circuit for resistive load



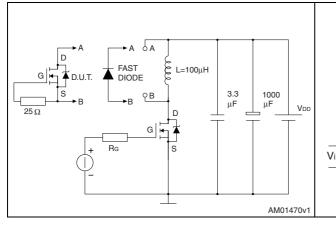


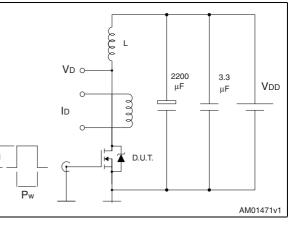
Gate charge test circuit

Figure 3.

Figure 4. Test circuit for inductive load switching and diode recovery times







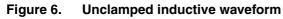
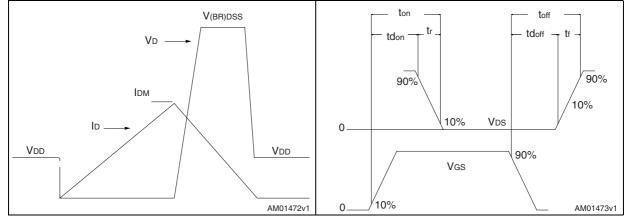


Figure 7. Switching time waveform





4 Package mechanical data

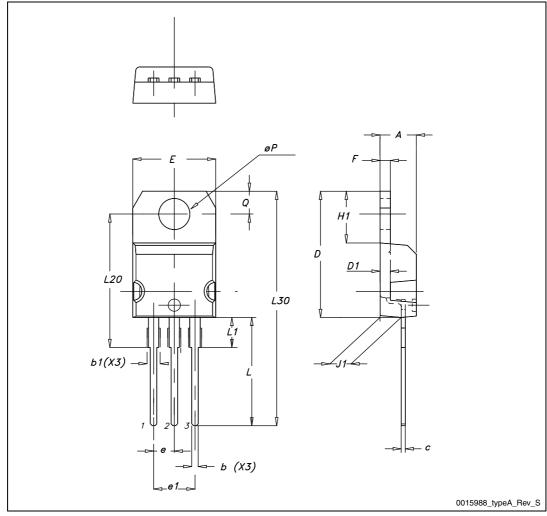
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| D' | mm | | | | |
|--------|-------|-------|-------|--|--|
| Dim. — | Min. | Тур. | Max. | | |
| А | 4.40 | | 4.60 | | |
| b | 0.61 | | 0.88 | | |
| b1 | 1.14 | | 1.70 | | |
| с | 0.48 | | 0.70 | | |
| D | 15.25 | | 15.75 | | |
| D1 | | 1.27 | | | |
| E | 10 | | 10.40 | | |
| е | 2.40 | | 2.70 | | |
| e1 | 4.95 | | 5.15 | | |
| F | 1.23 | | 1.32 | | |
| H1 | 6.20 | | 6.60 | | |
| J1 | 2.40 | | 2.72 | | |
| L | 13 | | 14 | | |
| L1 | 3.50 | | 3.93 | | |
| L20 | | 16.40 | | | |
| L30 | | 28.90 | | | |
| ØР | 3.75 | | 3.85 | | |
| Q | 2.65 | | 2.95 | | |

Table 9.TO-220 type A mechanical data



Figure 8. TO-220 drawing





5 Revision history

Table 10. Document revision history

| Date | Revision | Changes |
|-------------|----------|----------------|
| 12-Dec-2012 | 1 | First release. |



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Doc ID 024067 Rev 1

